

Technical specification

Gap Pad 5000S35

Description High thermal conductivity plus “S-Class” softness and conformability. Natural inherent tack reduces interfacial thermal resistance. Conforms to demanding contours and maintains structural integrity with little or no stress applied to fragile component leads. Fibreglass reinforced for puncture, shear and tear resistance. Excellent thermal performance at low pressures. Typical applications are CD and DVD ROM, PC board to chassis and memory packages/modules.

Properties	Unit	Value	Test method
Colour		Light Green	Visual
Reinforcement carrier		Fiberglass	
Thickness	Mm	0,508 to 3,175	ASTM D374
Inherent surface tack (1 sided)		2	
Density (Bulk rubber)	g/cc	3,6	ASTM D792
Heat Capacity	J/g-K	1,0	ASTM E1269
Hardness (Bulk Rubber)	Shore 00	35	ASTM D2240
Young's Modulus	kPa	121	ASTM D575
Continuous use temperature	°C	-60 to 200	
Dielectric Breakdown Voltage	Vac	>5000	ASTM D149
Dielectric Constant	1000 Hz	7,5	ASTM D150
Volume Resistivity	Ohm – meter	10 ⁹	ASTM D257
Flame rating	Mm	V-O	U.L. 94
Thermal conductivity	W/m-K	5,0	ASTM D5470
Thermal impedance at			
10 % deflection	°C-in ² /W 0,040" (3)	0,41	
20 % deflection	°C-in ² /W 0,040" (3)	0,34	
30 & deflection	°C-in ² /W 0,040" (3)	0,30	

This specification is given by our best knowledge and might be submitted to changes.